

PTO/SB/82 (01-06)

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REVOCATION OF POWER OF ATTORNEY WITH NEW POWER OF ATTORNEY AND CHANGE OF CORRESPONDENCE ADDRESS	Application Number	09/475,686
	Filing Date	December 30, 1999
	First named inventor	Bushan Gupta
	Art Unit	2632
	Examiner	V. H. Trieu
	Attorney Docket No.	99-R-156

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I hereby revoke all previous powers of attorney given in the above-identified application, and:

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☒ Please change the correspondence address for the above-identified application to:

☒ The address associated with Customer Number: **43785**

OR

☐ Firm or individual name

Address

City

State:

Zip:

Country

Telephone

Email:

I am (or authorized to act on behalf of) the:

☐ Applicant/Inventor

☒ Assignee of record of the entire interest. See 37 CFR 3.71.

Statement under 37 CFR 3.73(b) is enclosed

Signature of Applicant or Assignee of Record

Signature

Name

Philip Smith, V.P. Finance

Date

May 2, 2006

Telephone

510-420-2627

NOTE: Signatures of all the inventors or assignees of record of the entire interest or their representative(s) are required. Submit multiple forms if more than one signature is required. See below*.

This collection of information is required by 37 CFR 1.36. The information is required to obtain or retain a benefit by the public which is to file (and by the USPTO to process) an application. Confidentiality is governed by 35 U.S.C. 122 and 37 CFR 1.11 and 1.14. This collection is estimated to take 3 minutes to complete, including gathering, preparing, and submitting the completed application form to the USPTO. Time will vary depending upon the individual case. Any comments on the amount of time you require to complete this form and/or suggestions for reducing this burden, should be sent to the Chief Information Officer, U.S. Patent and Trademark Office, U.S. Department of Commerce, P.O. Box 1450, Alexandria, VA 22313-1450. DO NOT SEND FEES OR COMPLETED FORMS TO THIS ADDRESS. SEND TO: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.

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PTO/SR/06 (12-05) Approved for use through 07/31/2006. OMB 0651-0031
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STATEMENT UNDER 37 CFR 3.73(b)

Applicant/Patent Owner: UPEK, Inc.

Application No./Patent No./Control No.: 09/475,686

Filed/Issue Date: December 30, 1999

Entitled: Command Interface Using Fingerprint Sensor Input System

UPEK, Inc., a Delaware Corporation, states that it is:

1. ☒ the assignee of the entire right, title, and interest; or
2. ☐ an assignee of less than the entire right, title and interest

(The extent (by percentage) of its ownership interest is 100%) in the patent application/patent identified above by virtue of either:

A. ☐ An assignment from the inventor(s) of the patent application/patent identified above. The assignment was recorded in the United States Patent and Trademark Office at Reel _____, Frame _____, or a true copy of the original assignment is attached.

OR

B. ☒ A chain of title from the inventor(s), of the patent application/patent identified above, to the current assignee as follows:

1. From: Bhushan Gupta and Alan Kramer To: ST Microelectronics, Inc.

The document was recorded in the United States Patent and Trademark Office at Reel 010797, Frame 0142.

2. From: ST Microelectronics, Inc. To: UPEK, Inc.

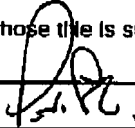
A true copy of the original assignment is attached.

☐ Additional documents in the chain of title are listed on a supplemental sheet.

As required by 37 CFR 3.73(b)(1)(i), the documentary evidence of the chain of title from the original owner to the assignee was, or concurrently is being, submitted for recordation pursuant to 37 CFR 3.11.

[NOTE: A separate copy (i.e., a true copy of the original assignment document(s)) must be submitted to Assignment Division in accordance with 37 CFR Part 3, to record the assignment in the records of the USPTO. See MPEP 302.08]

The undersigned (whose title is supplied below) is authorized to act on behalf of the assignee.

Signature			
Name	Phillip Smith, V.P. Finance		
Date	May 2, 2006	Telephone	510-420-2627

This collection of information is required by 37 CFR 3.73(b). The information is required to obtain or retain a benefit by the public which is to file (and by the USPTO to process) an application. Confidentiality is governed by 35 U.S.C. 122 and 37 CFR 1.11 and 1.14. This collection is estimated to take 12 minutes to complete, including gathering, preparing, and submitting the completed application form to the USPTO. Time will vary depending upon the individual case. Any comments on the amount of time you require to complete this form and/or suggestions for reducing this burden, should be sent to the Chief Information Officer, U.S. Patent and Trademark Office, U.S. Department of Commerce, P.O. Box 1450, Alexandria, VA 22313-1450. DO NOT SEND FEES OR COMPLETED FORMS TO THIS ADDRESS. SEND TO: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.

If you need assistance in completing the form, call 1-800-PTO-9199 and select option 2.

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PATENT ASSIGNMENT

WHEREAS, STMicroelectronics, Inc., a Delaware Corporation with its principal place of business located at 1310 Electronic Drive in Carrollton, Texas, and STMicroelectronics N.V. a company organized under the laws of Netherlands (collectively "ST"), own all legal and equitable right, title in the U.S. Patents listed in Annex 1 hereto ("Patents").

WHEREAS, Upek, Inc., a Delaware corporation with its principal place of business located at 2001 Center Street, Suite 500, Berkeley, California 94704 ("Upek"), is desirous of acquiring ST's entire right, title and interest in and to said patents, including the right to sue and recover damages for past and future infringement thereof.

NOW THEREFORE, be it known by all whom it may concern that for and in consideration of One Dollar (\$1.00), the receipt of which is hereby acknowledged, and other good and valuable consideration, ST hereby assigns to Upek all legal and equitable right, title and interest in and to the Patents, including any right to sue and recover damages for past and future infringement of the Patents.

ST further agrees that, should additional or further documentation of assignment be required for whatever reason, ST will, without further consideration, provide or execute such other information or documents as may be necessary upon Upek's reasonable request.

IN TESTIMONY WHEREOF, ST executes this assignment on the date set forth below.

STMicroelectronics, Inc

STMicroelectronics N.V.

By:

Lisa K. Jorgenson

By:

Name: Lisa Jorgenson

Name: A. Duthell

Title: VP of Intellectual Property
and Licensing.Title: Corporate Vice-President, Strategic Planning
and Human Resources.

Date: March 4, 2004

Date: March 4, 2004

Patent Assignment ST, Inc

PATENT ASSIGNMENT

WHEREAS, STMicroelectronics, Inc., a Delaware Corporation with its principal place of business located at 1310 Electronic Drive in Carrollton, Texas, and STMicroelectronics N.V. a company organized under the laws of Netherlands (collectively "ST"), own all legal and equitable right, title in the U.S. Patents listed in Annex 1 hereto ("Patents").

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IN TESTIMONY WHEREOF, ST executes this assignment on the date set forth below.

STMicroelectronics, Inc.

STMicroelectronics N.V.

By:

By:

Name: Lisa Jorgenson

Name: A. Dutheil

Title: VP of Intellectual Property
and Licensing.

Title: Corporate Vice-President, Strategic Planning
and Human Resources.

Date: March 4, 2004

Date: March 4, 2004

Patent Assignment ST, Inc

Annex 1

US Patent Application 09/169894: PCT US 99/23479 (from Veridicom)

Case No.	U.S. Pat. No.	Status	Title	Pending Foreign Counterparts
97-B-036C1	6,011,853	Issued	Solid state fingerprint sensor packaging apparatus & method	EP 88005195.4 JP 10-187248
97-B-037C2	6,483,331	Issued	Electrostatic discharge protection of a capacitive type fingerprint sensing array	EP 88307340.0 JP 10-258382
97-B-039C1	6,332,638	Issued	Touchpad providing screen cursor/point movement control	EP 88300406.4 JP 10-14176
97-B-072C1	6,311,508	Issued	Scanning capacitive semiconductor fingerprint detector	EP 89300181.7 JP 11-5762
97-B-072C2	6,380,816	Issued	Scanning capacitive semiconductor fingerprint detector	
97-B-073	6,408,087	Issued	Capacitive semiconductor user input device	EP 89300788.2 JP 11-5736
97-C-166C1	6,026,173	Issued	Packaging for silicon sensors	
98-B-089C1	6,346,733	Issued	Static charge dissipation pads for sensors	EP 8930533.7 JP 11-356318
98-B-82/86C1	6,440,814	Issued	Electrostatic discharge protection for sensors	EP 8930545.1 JP 11-366932
98-B-82/86C1	6,539,888	Issued	Electrostatic discharge protection for sensors	
98-B-82	6,501,284	Issued	Capacitive finger detection for fingerprint sensor	EP 01306372.9 JP 2001-957385
00-B-021	6,512,301	Issued	Enhanced fingerprint detection system	EP 0130704.3 JP 2001-338021
00-B-120	6,587,289	Issued	Fingerprint sensor power management detection of overcurrent	EP 02254352.1 JP 2002-823040
01-C-012	6,915,488	Issued	Fingerprint detector with scratch resistant surface & embedded ESD protection grid	EP 02253138.8 JP 2002-131644
Case No.	Appl. No.	Status	Title	Pending Foreign Counterparts
99-B-67	09/415,051	Abandoned	Enhanced fingerprint detection	
97-B-037C3	10/253,841	Pending	Electrostatic discharge protection of a capacitive type fingerprint sensing array	
99-B-089C1	10/040,861	Pending	Static charge dissipation pads for sensors	
03-C-03	03/643,808	Pending	Resistive finger detection for fingerprint sensor	EP 01306373.7 JP 2001-257940
99-B-156	03/475,686	Pending	Command interface using fingerprint sensor input system	EP 00311522.7 JP 2000-338753
99-B-67	03/658,540	Pending	Automatic wakeup recovery circuit for fingerprint sensor	
99-B-153	03/542,440	Pending	Method of and system for compensating for injection gradient in a capacitive sensing circuit array	EP 01303113.0 JP 2001-105676
99-B-160	03/537,633	Pending	Narrow array capacitive fingerprint imager	EP 01302011.4 JP 2001-31575
01-B-088	10/052,663	Pending	Capacitive pixel for fingerprint sensor	EP 02257454.5 JP 2002-320318
01-B-197	03/931,549	Pending	Improved sensing element arrangement for a fingerprint sensor	EP 02257610.8 JP 2002-344328
01-C-023	03/343,537	Pending	A solution & methodology for detecting surface damage on capacitive sensor integrated circuit	EP 02253633.6 JP 2002-252413
01-C-115	10/335,587	Pending	Imaging system with locator bar for accurate fingerprint recognition	
01-C-116	10/335,586	Pending	Imaging system with guide for accurate fingerprint recognition	
01-C-127	10/000,174	Pending	Capacitive fingerprint sensor with protective coating containing a conductive suspension	EP 02257614.0 2002-050076
01-VD-033C1	03/681,853	Pending	Protective Enclosure for Sensor Devices	EP 89303102.8 PCT US99/23473
01-C-137		Open	System of improvement to fingerprint recognition algorithm	
01-B-141		Open	Technique to identify real finger vs an artificially made one	
01-C-123		Open	Mechanical/procedural solution to the wet finger problem in biometric sensors	
01-C-130		Open	Apparatus & methodology to produce, in a compact device, an unspoofable biometric sensor with high match rates	
01-C-131		Open	Method & apparatus to increase the probability of correct fingerprint matching while eliminating spoofing	

Patent Assignment ST, Inc